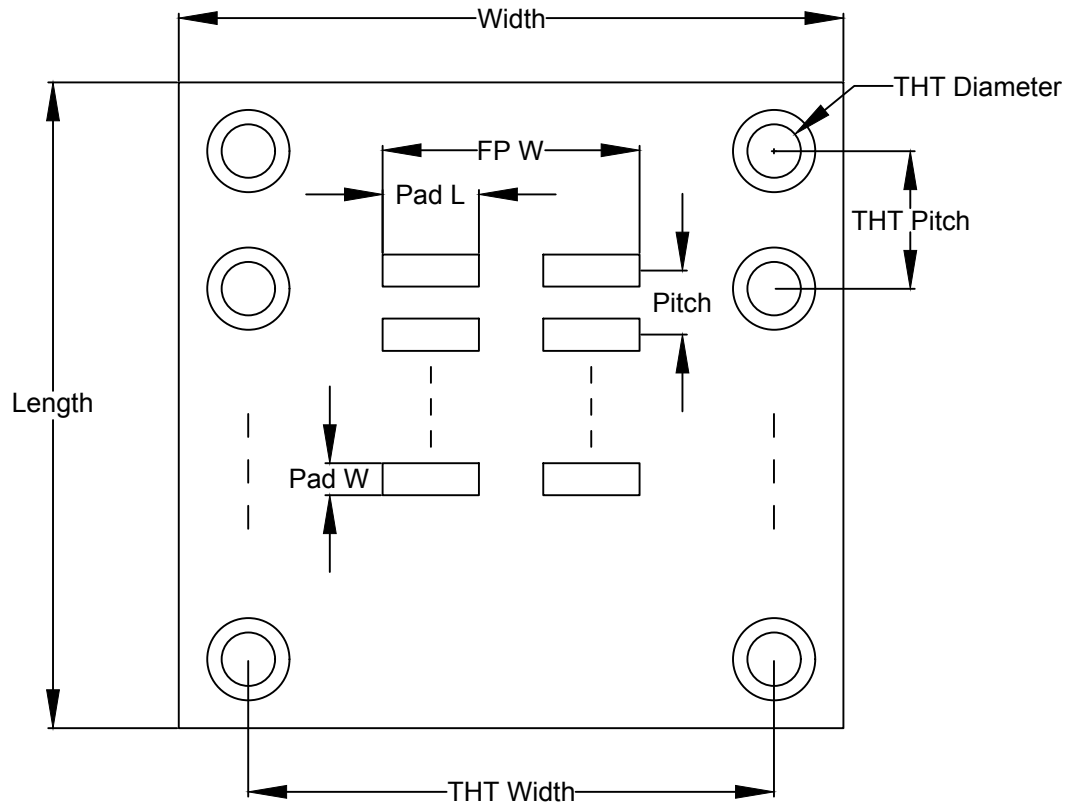


# Double-Sided SOIC/SOP/SSOP To DIP Breakout Board



(Not To Scale)

Board Dimensions						
Part #	Pin Count	Length (mm)	Width (mm)	THT Pitch (mm)	THT Diameter (mm)	THT Width (mm)
DE02008	8	11	12	2.54	1	7.6
DE02014	14	18.8	18.9	2.54	1	15.24
DE02016	16	21.4	18.9	2.54	1	15.24
DE02018	18	23.8	18.9	2.54	1	15.24
DE02020	20	26.4	17.8	2.54	1	15.24
DE02024	24	31.5	18.9	2.54	1	15.24
DE02028	28	36.8	18.9	2.54	1	15.24

Front Footprint				
Part #	Pitch (mm)	Pad W (mm)	Pad L (mm)	FP W (mm)
DE02008	1.27	0.6	4.0	9.2
DE02014	1.27	0.6	4.0	9.2
DE02016	1.27	0.6	4.0	9.2
DE02018	1.27	0.6	4.0	9.2
DE02020	1.27	0.6	4.0	11.2
DE02024	1.27	0.7	4.5	11.9
DE02028	1.27	0.7	4.5	11.9

Back Footprint				
Part #	Pitch (mm)	Pad W (mm)	Pad L (mm)	FP W (mm)
DE02008	0.65	0.35	4.0	9.2
DE02014	0.65	0.35	4.0	9.2
DE02016	0.65	0.35	4.0	9.2
DE02018	0.65	0.35	4.0	9.2
DE02020	0.65	0.35	4.0	11.2
DE02024	0.65	0.35	4.5	10.6
DE02028	0.65	0.35	4.5	10.9